

A NOVEL BONDING STRUCTURE FOR A HARD DISK DRIVE
SUSPENSION USING ANISOTROPIC CONDUCTIVE FILM

ABSTRACT OF THE INVENTION

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A plurality of bonding structures and their forming methods for bonding a FPC to a bonding pad, in particular a bonding pad of a wireless suspension in a head gimbal assembly, using anisotropic conductive adhesive; such structures eliminate the spring-back force in typical anisotropic bonding to ensure durable bonding. At the same time, these structures also allow for reworkability under which the bonded parts can be separated easily.

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